PACKAGE MARKING

ABSTRACT

Marking apparatus and method for marking semiconductor chip devices with an identification mark comprises a support for holding the chip devices simultaneously in a required spatial arrangement, an optical inspection device which simultaneously views those devices which are in a field of view and which indicates, via an output, positions at which the chip devices are located, comparator means which compares the output of the inspection device with predetermined data and a marking device operable in response to a control signal from the comparator means to mark selectively those chip devices within the field of view which are positioned in desired locations.

(FIg. 1D)